Heraeus

C2130

Conductor

Description

C2130 is a Pd/Ag composition designed for applications where more leach resistance is required. The C2130 conductor is suitable for a wide variety of applications such as automotive electronics, power hybrids and commercial circuits where more stringent requirements exist. It exhibits excellent solderability, aged adhesion properties and is aluminium wire bondable.

Key Features

- Excellent solderability and leach resistance
- Excellent long term adhesion
- Good AI wire bond adhesion (initial and aged)



This picture does not show the packaging of C2130 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties	
Viscosity	150-220 Kcps Brookfield HBT SC4-14 spindle, 6R utility cup at 10 rpm, 25 °C
Solids	79.0 ± 1.0 %
Alloy Ratio	03:01
Coverage	75 cm ² /g at 12 um fired film thickness
Metal	AgPd
Color	Dark Grey
Recommended Processing Guide	

Process 850 °C peak temperature. 10 minutes at Temperature peak. Total cycle time 30-60 minutes.

Film 10-15 um Thickness

(TDS)

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Warranty

6 months

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